1. Package summary

<table>
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<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Min</th>
<th>Typ</th>
<th>Nom</th>
<th>Max</th>
<th>Unit</th>
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<tr>
<td>D</td>
<td>package length</td>
<td>14.8</td>
<td>-</td>
<td>15</td>
<td>15.2</td>
<td>mm</td>
</tr>
<tr>
<td>E</td>
<td>package width</td>
<td>14.8</td>
<td>-</td>
<td>15</td>
<td>15.2</td>
<td>mm</td>
</tr>
<tr>
<td>A</td>
<td>seated height</td>
<td>[tbd]</td>
<td>-</td>
<td>1.65</td>
<td>1.65</td>
<td>mm</td>
</tr>
<tr>
<td>A₂</td>
<td>package height</td>
<td>0.95</td>
<td>-</td>
<td>1.05</td>
<td>1.2</td>
<td>mm</td>
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<tr>
<td>n₂</td>
<td>actual quantity of termination</td>
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<td>-</td>
<td>156</td>
<td>-</td>
<td>-</td>
</tr>
</tbody>
</table>

Table 1. Package summary
2. Package outline

LBGA156: plastic low profile ball grid array package; 156 balls; body 15 x 15 x 1.05 mm

Fig. 1. Package outline LBGA156 (SOT700-1)
3. Soldering

Footprint information for reflow soldering of LBGA156 package

Generic footprint pattern
Refer to the package outline drawing for actual layout

solder land
solder paste deposit
solder land plus solder paste
occupied area
solder resist
detail X

DIMENSIONS in mm

<table>
<thead>
<tr>
<th>P</th>
<th>SL</th>
<th>SP</th>
<th>SR</th>
<th>Hx</th>
<th>Hy</th>
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<tbody>
<tr>
<td>1.00</td>
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<td>0.450</td>
<td>0.600</td>
<td>15.575</td>
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</table>

Fig. 2. Reflow soldering footprint for LBGA156 (SOT700-1)
4. Legal information

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